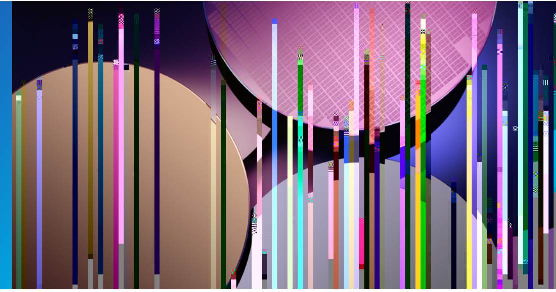
Brochure

MicroSense® C200-CSW1

Wafer Geometry Measurement System

Standard metrics like wafer thickness, shape, global f atness and edge/site f atness measurements



Automatic, non-contact measurement of bare, patterned and wafers with thin f lms—150mm & 200mm diameter

The MicroSense® C200-CSW1 measurement system provides full wafer, high speed geometry measurement of semiconductor wafers using non-contact capacitance sensors with nanometer level thickness resolution. The system measures the thickness, f atness, bow and warp of the wafer in compliance with SEMI standards. Designed for maximum versatility, the system can measure 150mm and 200mm diameter wafers with over 150,000 data points on each wafer to generate high resolution wafer maps.

- Automatically calibrates before and after every measurement for best repeatability and accuracy
- Automatically loads and measures wafers on precision air bearing X-Y stage from 2 cassette stations
- Industry unique, mate m u a tutv › m mQ sd e

System Configuration

- Non-contact precision air bearing XY stage
- Single paddle robot, slot scanner and pre-aligner; kinematic 3-point wafer holder
- Dual open cassette
- Integrated light curtain safety system
- Dual-sided SEMI Standard compliant capacitance